

### REMARKS

Reconsideration of the above-referenced application in view of the above amendment, and of the following remarks, is respectfully requested.

Claims 1-17 are pending in this case. Claims 1, 2, 11, and 12 are amended herein. Claims 18-27 are cancelled.

The Examiner rejected claims 1-3, 5-7, 9-13 and 15-17 under 35 U.S.C. § 102(b) as being anticipated by Hasegawa (U.S. Patent 5,646,440).

Applicant respectfully submits that amended claim 1 is unanticipated by Hasegawa as there is no disclosure or suggestion of a liner comprising a compound including silicon and carbon, wherein the liner is positioned between at least a portion of the dielectric layer and a conductive element. Hasegawa teaches a first dielectric film 15 covering a conductive interconnect 14 and a second dielectric film 16 located between conductive interconnects 14. The first conductive film may comprise silicon oxide, silicon oxynitride, or silicon nitride. There is no disclosure or suggestion of a liner comprising a compound of silicon and carbon. Accordingly, Applicant respectfully submits that claim 1 and the claims dependent thereon are unanticipated by Hasegawa.

Applicant respectfully submits that amended claim 11 is unanticipated by Hasegawa as there is no disclosure or suggestion of a liner positioned between at least a portion of a dielectric layer and a conductive element, the liner comprising a compound including silicon and carbon. As discussed above, Hasegawa teaches a first dielectric film of silicon-oxide, silicon-oxynitride, or silicon nitride. Hasegawa does not disclose or suggest a liner comprising a compound of silicon and carbon. Accordingly, Applicant respectfully submits that claim 11 and the claims dependent thereon are unanticipated by Hasegawa.

The Examiner rejected claims 4 and 14 under 35 U.S.C. § 103(a) as being unpatentable over Hasegawa as applied to Claim 1, and further in view of Schrantz et al. (U.S. Patent 5,650,639).

Applicant respectfully submits that claim 4 is patentable over Hasegawa in view of Schrantz as there is no disclosure or suggestion in the references of a liner comprising a compound including silicon and carbon, wherein the liner is positioned between at least a portion of the dielectric layer and a conductive element, as required by claim 1, from which claim 4 depends. As discussed above, Hasegawa does not disclose or suggest this claim limitation. Schrantz is apparently added by the Examiner to teach a polysilicon conductive element. Accordingly, Applicant respectfully submits that claim 4 is patentable over the references.

Applicant respectfully submits that claim 14 is similarly patentable over the references.

The Examiner rejected claim 8 under 35 U.S.C. § 103(a) as being unpatentable over Hasegawa as applied to Claim 1, and further in view of Chooi et al. (U.S. Patent No. 6,465,888 B2).

Applicant respectfully submits that claim 8 is patentable over Hasegawa in view of Chooi as there is no disclosure or suggestion in the references of a liner comprising a compound including silicon and carbon, wherein the liner is positioned between at least a portion of the dielectric layer and a conductive element, as required by claim 1, from which claim 8 depends. As discussed above, Hasegawa does not disclose or suggest this claim limitation. Chooi is added by the Examiner to teach PTFE as a dielectric layer. Accordingly, Applicant respectfully submits that claim 8 is patentable over the references.

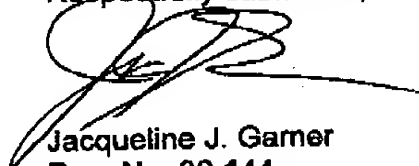
The other references cited by the Examiner have been reviewed, but are not felt to come within the scope of the claims as amended.

Attached hereto is a marked up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "**Version with Markings to Show Changes Made.**"

In light of the above, Applicant respectfully requests withdrawal of the Examiner's rejections and allowance of claims 1-17. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

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Respectfully submitted,



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### **Version with Markings to Show Changes Made**

Claim 1 is amended as follows:

1. (amended) An integrated circuit structure, comprising:
  - a plurality of solid state electronic devices;
  - a plurality of conductive elements electrically coupling the electronic devices;
  - a dielectric layer positioned between two or more of the conductive elements; and
  - a liner comprising a compound including silicon and [an element selected from the group consisting of] carbon[ and nitrogen], the liner positioned between at least a portion of the dielectric layer and a conductive element.

Claim 2 is amended as follows:

2. (amended) The integrated circuit structure of Claim 1, wherein the liner is selected from the group consisting of [silicon nitride, silicon oxy-nitride, silicon boron-nitride,] silicon carbide, silicon oxy-carbide, and silicon boron-carbide.

Claim 11 is amended as follows:

11. (amended) An integrated circuit structure comprising a liner positioned between at least a portion of a dielectric layer and a conductive element, the liner comprising a compound including silicon and [an element selected from the group consisting of] carbon[ and nitrogen].

Claim 12 is amended as follows:

12. (amended) The integrated circuit structure of Claim 11, wherein the liner is selected from the group consisting of [silicon nitride, silicon oxy-nitride, silicon boron-nitride,] silicon carbide, silicon oxy-carbide, and silicon boron-carbide.